

Title (en)
HOUSING FOR A COMPUTER

Title (de)
GEHÄUSE FÜR EINEN COMPUTER

Title (fr)
BOITIER D'ORDINATEUR

Publication
EP 1864197 A1 20071212 (DE)

Application
EP 06723872 A 20060330

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Abstract (en)
[origin: WO2006103072A1] The invention relates to a housing for a computer or multi-media equipment or similar comprising at least one heat-generating component, said housing having a respective cooling body on opposing walls and a heat conduction conduit that is thermally coupled to the heat-generating component. The housing is characterised in that the heat conduction conduit runs along both opposing walls and is thermally coupled to the cooling bodies, whereby heat from the heat-generating component can be dissipated from the housing via the heat conduction conduit and the cooling bodies. By running the heat conduction conduit along opposing walls, heat is transferred in a rapid, uniform manner to the entire surface of the cooling bodies that are contained in the walls.

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